



DAGSTUHL
ARTIFACTS SERIES

Volume 8 | Issue 2 | June 2022

**Special Issue of the 36th European Conference on
Object-Oriented Programming (ECOOP 2022)**

Edited by

Alessandra Gorla
Stefan Winter


ISSN 2509-8195

DARTS Special Issue Editors

Alessandra Gorla

IMDEA Software Institute, Madrid, Spain
alessandra.gorla@imdea.org

Stefan Winter

LMU Munich, Germany
sw@stefan-winter.net
 <https://orcid.org/0000-0001-8244-995X>

ACM Classification 2012

Software and its engineering

Published online and open access by

Schloss Dagstuhl – Leibniz-Zentrum für Informatik
GmbH, Dagstuhl Publishing, Saarbrücken/Wadern,
Germany.

Online available at

<http://drops.dagstuhl.de/darts>.

Publication date

June 2022

License

This work is licensed under a Creative Commons
Attribution 4.0 International license (CC BY 4.0):
[https://creativecommons.org/licenses
/by/4.0](https://creativecommons.org/licenses/by/4.0).



In brief, this license authorizes each
and everybody to share (to copy,
distribute and transmit) the work under the follow-
ing conditions, without impairing or restricting the
authors' moral rights:

- Attribution: The work must be attributed to its authors.

The copyright is retained by the corresponding au-
thors.

Aims and Scope

The Dagstuhl Artifacts Series (DARTS) publishes
evaluated research data and artifacts in all areas of
computer science. An artifact can be any kind of
content related to computer science research, e.g.,
experimental data, source code, virtual machines
containing a complete setup, test suites, or tools.

Contact

Schloss Dagstuhl – Leibniz-Zentrum für Informatik
DARTS, Editorial Office
Oktavie-Allee, 66687 Wadern, Germany
publishing@dagstuhl.de

Digital Object Identifier

10.4230/DARTS.8.2.0

<http://www.dagstuhl.de/darts>

■ Contents

Preface	
<i>Alessandra Gorla and Stefan Winter</i>	0:vii
Artifact Evaluation Process	
.....	0:ix
Artifact Evaluation Committee	
.....	0:xi

Artifacts

How to Take the Inverse of a Type (Artifact)	
<i>Daniel Marshall and Dominic Orchard</i>	1:1–1:3
Defining Corecursive Functions in Coq Using Approximations (Artifact)	
<i>Vlad Rusu and David Nowak</i>	2:1–2:2
Compiling Volatile Correctly in Java (Artifact)	
<i>Shuyang Liu, John Bender, and Jens Palsberg</i>	3:1–3:2
Direct Foundations for Compositional Programming (Artifact)	
<i>Andong Fan, Xuejing Huang, Han Xu, Yaozhu Sun, and Bruno C. d. S. Oliveira</i>	4:1–4:3
Elementary Type Inference (Artifact)	
<i>Jinxu Zhao and Bruno C. d. S. Oliveira</i>	5:1–5:2
Qilin: A New Framework for Supporting Fine-Grained Context-Sensitivity in Java Pointer Analysis (Artifact)	
<i>Dongjie He, Jingbo Lu, and Jingling Xue</i>	6:1–6:3
Automatic Root Cause Quantification for Missing Edges in JavaScript Call Graphs (Artifact)	
<i>Madhurima Chakraborty, Renzo Olivares, Manu Sridharan, and Behnaz Hassanshahi</i>	7:1–7:5
Functional Programming for Distributed Systems with XC (Artifact)	
<i>Giorgio Audrito, Roberto Casadei, Ferruccio Damiani, Guido Salvaneschi, and Mirko Viroli</i>	8:1–8:4
Stay Safe Under Panic: Affine Rust Programming with Multiparty Session Types (Artifact)	
<i>Nicolas Lagaillardie, Romyana Neykova, and Nobuko Yoshida</i>	9:1–9:16
Verified Compilation and Optimization of Floating-Point Programs in CakeML (Artifact)	
<i>Heiko Becker, Robert Rabe, Eva Darulova, Magnus O. Myreen, Zachary Tatlock, Ramana Kumar, Yong Kiam Tan, and Anthony Fox</i>	10:1–10:2



Low-Level Bi-Abduction (Artifact) <i>Lukáš Holík, Petr Peringer, Adam Rogalewicz, Veronika Šoková, Tomáš Vojnar, and Florian Zuleger</i>	11:1–11:6
REST: Integrating Term Rewriting with Program Verification (Artifact) <i>Zachary Grannan, Niki Vazou, Eva Darulova, and Alexander J. Summers</i>	12:1–12:2
A Deterministic Memory Allocator for Dynamic Symbolic Execution (Artifact) <i>Daniel Schemmel, Julian Büning, Frank Busse, Martin Nowack, and Cristian Cadar</i>	13:1–13:2
Ferrite: A Judgmental Embedding of Session Types in Rust (Artifact) <i>Ruo Fei Chen, Stephanie Balzer, and Bernardo Toninho</i>	14:1–14:2
A Self-Dual Distillation of Session Types: Mechanized Proofs (Artifact) <i>Jules Jacobs</i>	15:1–15:2
Prisma: A Tierless Language for Enforcing Contract-Client Protocols in Decentralized Applications (Artifact) <i>David Richter, David Kretzler, Pascal Weisenburger, Guido Salvaneschi, Sebastian Faust, and Mira Mezini</i>	16:1–16:3
Union Types with Disjoint Switches (Artifact) <i>Baber Rehman, Xuejing Huang, Ningning Xie, and Bruno C. d. S. Oliveira</i>	17:1–17:6
Global Type Inference for Featherweight Generic Java – Prototype Implementation (Artifact) <i>Andreas Stadelmeier, Martin Plümicke, and Peter Thiemann</i>	18:1–18:4
API Generation for Multiparty Session Types, Revisited and Revised Using Scala 3 (Artifact) <i>Guillermína Cledou, Luc Edixhoven, Sung-Shik Jongmans, and José Proença</i>	19:1–19:4
Concolic Execution for WebAssembly (Artifact) <i>Filipe Marques, José Fragoso Santos, Nuno Santos, and Pedro Adão</i>	20:1–20:3
Design-by-Contract for <i>Flexible</i> Multiparty Session Protocols (Artifact) <i>Lorenzo Gheri, Ivan Lanese, Neil Sayers, Emilio Tuosto, and Nobuko Yoshida</i> ...	21:1–21:5
Accumulation Analysis (Artifact) <i>Martin Kellogg, Narges Shadab, Manu Sridharan, and Michael D. Ernst</i>	22:1–22:3
JavaScript Sealed Classes (Artifact) <i>Manuel Serrano</i>	23:1–23:4
PEDROID: Automatically Extracting Patches from Android App Updates (Artifact) <i>Hehao Li, Yizhuo Wang, Yiwei Zhang, Juanru Li, and Dawu Gu</i>	24:1–24:2
Synchron – An API and Runtime for Embedded Systems (Artifact) <i>Abhiroop Sarkar and Bo Joel Svensson</i>	25:1–25:2
What If We Don’t Pop the Stack? The Return of 2nd-Class Values (Artifact) <i>Anzhelo Xhebraj, Oliver Bračevac, Guannan Wei, and Tiark Rompf</i>	26:1–26:2

■ Preface

ECOOP has a long-standing tradition of offering artifact evaluation dating back to 2013. For the first time this year, though, the artifact evaluation process involved every single paper submission to ECOOP 2022, rather than just accepted papers, and happened in parallel with the paper review process. Besides providing feedback on the artifacts irrespective of paper acceptance, evaluation results were made available to the technical PC. Artifact submissions could thus provide more insights on the technical contributions described in the papers, and help to improve the overall review process.

To handle the higher review load that such a process entails, we recruited an artifact evaluation committee that was almost twice as large as for last year's ECOOP and included both experienced and novice artifact reviewers. The submission deadlines for artifacts were just 10 days after the paper deadlines for both submission rounds. We received a total of 57 submissions (39 for R1 and 18 for R2). After a kick-the-tires review and author response phase, during which authors had the opportunity to clarify or address technical issues with their submissions, each submitted artifact was reviewed by at least three committee members, leading to an overall review load of 4-5 artifact reviews per committee member.

Following the positive experience with adopting ACM's artifact badges for ECOOP 2021, we adopted the same badging policies for ECOOP 2022. The artifact evaluation committee positively evaluated 46 submissions (33/13 for R1/R2) as *functional* or *reusable*, out of which 25 belong to papers to appear in the technical program of ECOOP 2022. 7 submitted artifacts (4/3 in R1/R2) that did not pass the bar for the *functional* and *reusable* badges, were found eligible for the *available* badge, 2 of which are associated with papers accepted for presentation at ECOOP 2022 (both from R1).

In order to streamline the artifact review process and to decouple artifact from paper review aspects, we asked authors to submit documentation of explicit *claims* in a pre-specified format that the artifact evaluation committee checked the artifacts against. At the same time, the PC could assess the *importance of these claims* for the submitted papers as a frame of reference for the strength of support for the paper that an artifact can provide. This separation greatly facilitated the artifact evaluation committee's discussions regarding which badges to award.

The smooth and thorough artifact evaluation process would have not been possible without the 39 members of the committee, who handled the artifact review workload and contributed to the technical PC discussions with great dedication. We would like to thank them for their valuable work and the inspiring discussions. We would also like to thank the ECOOP 2022 program committee chairs Jan Vitek and Karim Ali for the pleasant and productive interactions over the coordination of the paper and artifact review processes and the Dagstuhl Publishing team for their assistance with preparing this DARTS volume.

Alessandra Gorla

Artifact Evaluation Co-chair

IMDEA Software Institute

Stefan Winter

Artifact Evaluation Co-chair

Ludwig-Maximilians-Universität München

■ Artifact Evaluation Process

With ECOOP’s long standing tradition of artifact evaluations, the artifact review process for ECOOP 2022 builds on a wealth of experiences and insights from previous years and adopts concepts that have proven successful, such as the ‘kick-the-tires’ review phase and the adoption of the ACM’s badging scheme. The details of the process are documented in the call for artifacts (<https://doi.org/10.5281/zenodo.6553744>), the artifact submission template (<https://doi.org/10.5281/zenodo.5720714>), and an artifact review template (<https://doi.org/10.5281/zenodo.5750738>) that we provided as guidance for artifact reviewers. In the following we briefly highlight the changes compared to previous years’ evaluations.

Badges

Following the first adoption of ACM’s artifact badges for ECOOP 2021, we adopted the same badging policy, but changed the badges’ sub-branding for ECOOP. We are grateful to Ferruccio Damiani, ACM’s Scott Delman and Wayne Graves, the ECOOP 2021 artifact evaluation chairs William G. J. Halfond and Quentin Stiévenart, and Dagstuhl Publishing’s Michael Wagner, who all provided help and guidance in the badge adoption and branding processes.

Coupling Paper Reviews with Artifact Evaluations

The biggest changes for this year’s artifact evaluation result from a tight coupling with the paper review process. The goal of this coupling was to support the paper review process by making positive insights from the artifact evaluation accessible to the technical PC. While paper and artifact submissions were still handled separately (with artifact submission deadlines 10 days after the paper deadlines) and in different submission systems, information from the artifact reviews was carried over to the technical PC by having artifact reviewers serving as the external review committee for papers. This change had important implications for the review process:

- The load for the artifact evaluation committee increased, because committee members had to handle paper reviews in addition to artifact reviews. Moreover, artifact reviews were no longer conditioned on paper acceptance, which led to a higher number of artifact submissions to be reviewed. We addressed the higher load by (a) recruiting a committee almost twice as large as the previous year’s, (b) involving mostly experienced artifact reviewers, and (c) streamlining the review process and providing more extensive guidance and evaluation criteria to reviewers.
- To ensure that artifact reviews provide useful information for the paper reviews, we asked the authors of artifact submissions to provide precise claims regarding their artifacts’ functionality and reusability. These claims did not only provide a clear frame of reference for the reviewers’ evaluation of the artifacts. At the same time, it provided the technical PC with clear information which conclusions in the papers the authors consider as backed up by their artifacts. The artifact evaluation outcome provided information whether the artifacts indeed supported these expectations expressed by the authors themselves. In addition, the submission template for these claims (<https://doi.org/10.5281/zenodo.572071>) provided additional information about the artifact to reviewers in a uniform format.

■ Artifact Evaluation Committee

Jie An
Max Planck Institute for Software Systems
Germany

Oliver Bracevac
Purdue University
United States of America

Jonathan Immanuel Brachthäuser
University of Tübingen
Germany

Michele Chiari
Politecnico di Milano
Italy

Emanuele D'Oswaldo
MPI-SWS
Germany

Hoang-Hai Dang
MPI-SWS
Germany

Luigi De Simone
Università degli Studi di Napoli Federico II
Italy

Vlastimil Dort
Charles University
Czech Republic

Olivier Flückiger
Northeastern University
United States of America

Dongjie He
UNSW
Australia

Vojtěch Horký
Charles University
Czech Republic

Chiao Hsieh
University of Illinois at Urbana-Champaign
United States of America

Matthieu Jimenez
SnT, University of Luxembourg
Luxembourg

David Justo
Microsoft
United States of America

Ifaz Kabir
University of Alberta
Canada

Sven Keidel
TU Darmstadt
Germany

Steven Keuchel
Vrije Universiteit Brussel
Belgium

Chaitanya Koparkar
Indiana University
United States of America

Paulette Koronkevich
University of British Columbia
Canada

Martin Kruliš
Charles University, Faculty of Mathematics
and Physics
Czech Republic

Petr Maj

Kristóf Marussy
Budapest University of Technology and
Economics
Hungary

Toni Mattis
Hasso Plattner Institute, University of
Potsdam
Germany

Tomoki Nakamaru
The University of Tokyo
Japan

Krishna Narasimhan
TU Darmstadt
Germany

Jonas Norlinder
Uppsala University
Sweden

36th European Conference on Object-Oriented Programming (ECOOP 2022).

Editors: Alessandra Gorla and Stefan Winter



DAGSTUHL

ARTIFACTS SERIES

Dagstuhl Artifacts Series

Schloss Dagstuhl – Leibniz-Zentrum für Informatik, Dagstuhl Publishing, Germany

Markus Raab
Markus Raab Vienna University of
Technology
Austria

Baber Rehman
University of Hong Kong

Patrick Rein
Hasso Platter Institute, University of
Potsdam
Germany

Alex Renda
MIT CSAIL
United States of America

Michael Schröder
TU Wien
Austria

Lars Schütze
Technische Universität Dresden
Germany

Somesh Singh
Indian Institute of Technology Madras
India

Quentin Stiévenart
Vrije Universiteit Brussel
Belgium

Anish Tondwalkar
Google Inc.
United States of America

Pascal Weisenburger
University of St.Gallen
Germany

Junwen Yang
university of chicago
United States of America

Wenjia Ye
The University of Hong Kong
China

Chengyu Zhang
East China Normal University
China